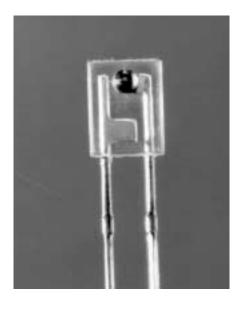
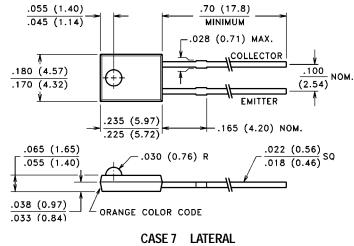
.025" NPN Phototransistors

Molded Lensed Lateral Package



PACKAGE DIMENSIONS inch (mm)



CHIP TYPE: 25T

PRODUCT DESCRIPTION

A small area high speed NPN silicon phototransistor mounted in a lensed, side looking, transparent plastic, transfer molded package. These devices are spectrally and mechanically matched to the VTE717xH series of IREDs.

ABSOLUTE MAXIMUM RATINGS

(@ 25°C unless otherwise noted)

Maximum Temperatures	
Storage Temperature:	-40°C to 85°C
Operating Temperature:	-40°C to 85°C
Continuous Power Dissipation:	50 mW
Derate above 30°C:	0.91 mW/°C
Maximum Current:	25 mA
Lead Soldering Temperature:	260°C
(1.6 mm from case, 5 sec. max.)	

RoHS Compliant



ELECTRO-OPTICAL CHARACTERISTICS @ 25°C (See also typical curves, pages 91-92)

Part Number	Light Current			Dark Current		Collector Breakdown	Emitter Breakdown	Saturation Voltage	Rise/Fall Time	Angular Response θ _{1/2}
	lç			I _{CEO}		V _{BR(CEO)}	V _{BR(ECO)}	V _{CE(SAT)}	t _R /t _F	
	mA H		H = 0		l _C = 100 μA H = 0	l _E = 100 μA H = 0	l _C = 1.0 mA H = 400 fc	l _C = 1.0 mA R _L = 100 Ω		
	Min.	Max.	fc (mW/cm ²) V _{CE} = 5.0 V	(nA) Max.	V _{CE} (Volts)	Volts, Min.	Volts, Min.	Volts, Max.	µsec, Typ.	Тур.
VTT7122H	1.0		100 (5)	100	10	30	5.0	0.25	2.0	±36°
VTT7123H	2.0	_	100 (5)	100	10	30	5.0	0.25	2.0	±36°
VTT7125H	4.5	_	100 (5)	100	10	30	5.0	0.25	2.0	±36°

Refer to General Product Notes, page 2.